



BOARD LEVEL COOLING - 3750

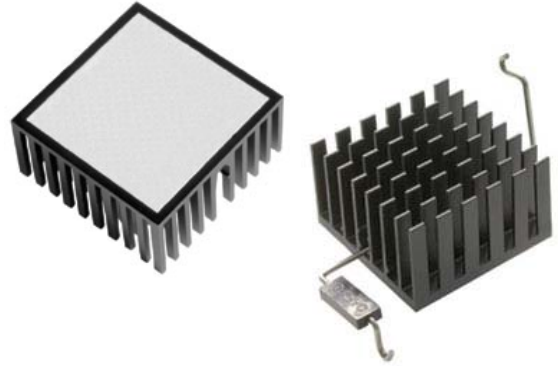
3750 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative Image Only.

ORDERING INFORMATION

Part Number	Device Type
375024B00032G	BGA, FPGA
375024B60024G	BGA, FPGA

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options: 375024B00032G	Tape
Device Attachment Options: 375024B60024G	Solder Anchor Clip
Thermal Interface Material: 375024B00032G	T411 Chomerics Tape for All Surfaces
Thermal Interface Material: 375024B60024G	T766 Chomerics Phase Change for All Surfaces

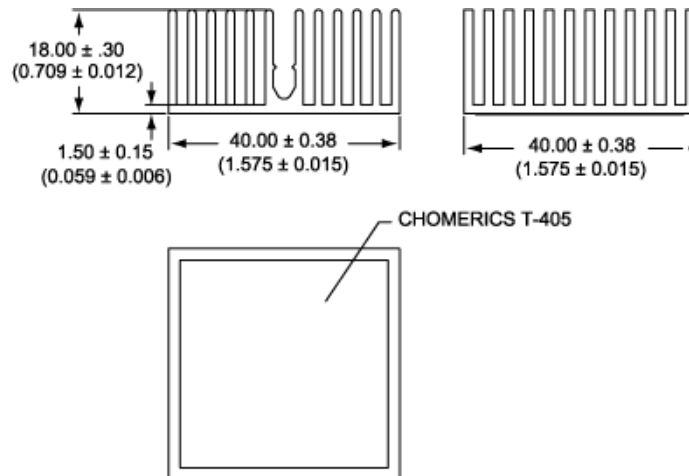


Property	Details
Heat Sink Width (mm)	40.00
Heat Sink Length (mm)	40.00
Heat Sink Height (mm)	18.00
Heat Sink Mounting Direction	Horizontal, Vertical

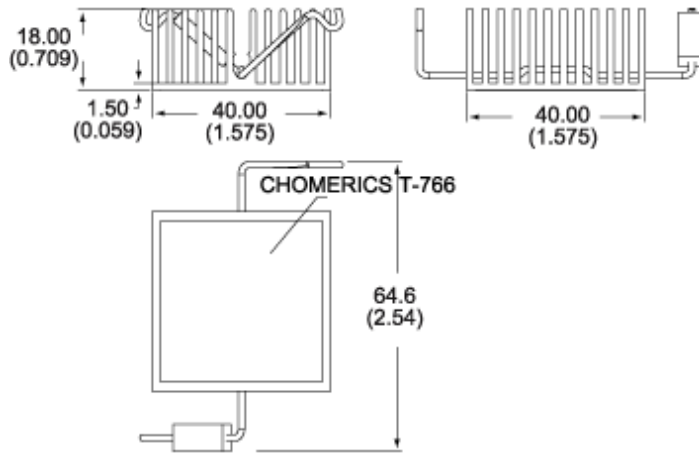
MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

Part Number: 375024B00032G



Part Number: 375024B60024G



Mounting Details:

